

20V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
	25mΩ @ V _{GS} = 4.5V	7.9A
001/	29mΩ @ Vgs = 2.5V	7.2A
20V	39mΩ @ V _{GS} = 1.8V	6.1A
	95mΩ @ V _{GS} = 1.5V	4.0A

Description

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- **Battery Management Application**
- **Power Management Functions**
- **DC-DC Converters**

Features

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Fast Switching Speed
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

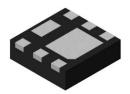
Mechanical Data

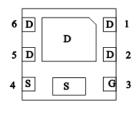
- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.0065 grams (Approximate)

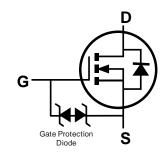
U-DFN2020-6 (Type F)











Top View

Bottom View

Pin Out **Bottom View**

Internal Schematic

Ordering Information (Note 4)

Part Number	Reel Size (inches)	Quantity per Reel
DMN2028UFDF-7	7	3,000
DMN2028UFDF-13	13	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/



Marking Information

Site 1





ND or NC = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Year	2015		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	С		Н	I	J	K	L	M	N	0	Р	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2





ND or NC = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = week 27; z represents week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2015	 2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	5	 0	1	2	3	4	5	6	7	8	9

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Υ	Z



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	20	V		
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 6) Ves - 4.5V	Steady State	T _A = +25°C T _A = +70°C	lo	7.9 6.3	А
Continuous Drain Current (Note 6) V _{GS} = 4.5V	t<5s	T _A = +25°C T _A = +70°C	ΙD	9.4 7.5	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I_{DM}	40	Α
Continuous Source-Drain Diode Current T _A = +25°C			Is	2	Α
Avalanche Current (Note 7) L = 0.1mH	las	12	Α		
Avalanche Energy (Note 7) L = 0.1mH			E _{AS}	8	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit	
Total Dower Discipation (Note 5)	T _A = +25°C	D-	0.66	W	
Total Power Dissipation (Note 5)	T _A = +70°C	PD	0.42	VV	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	Rеja	186	°C/W	
memial Resistance, Junction to Ambient (Note 5)	t<5s	Көја	135	C/VV	
Total Power Dissipation (Note 6)	T _A = +25°C	Pn	2.03	W	
Total Power Dissipation (Note 6)	T _A = +70°C	PD	1.31		
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	D	64		
memiai Resistance, Junction to Ambient (Note 6)	t<5s	$R_{\theta JA}$	43	°C/W	
Thermal Resistance, Junction to Case (Note 6)	Steady state	Rejc	18		
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C	

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)	-					•	
Drain-Source Breakdown Voltage	BVDSS	20	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	IDSS	_	_	1	μΑ	V _{DS} = 20V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)						•	
Gate Threshold Voltage	V _{GS(TH)}	0.5	1	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
			15	25		$V_{GS} = 4.5V, I_{D} = 4A$	
Static Drain-Source On-Resistance	D- avan		18	29	mΩ	$V_{GS} = 2.5V, I_{D} = 4A$	
Static Dialif-Source Off-Resistance	R _{DS(ON)}	_	24	39	11122	$V_{GS} = 1.8V, I_D = 4A$	
			35	95		$V_{GS} = 1.5V, I_{D} = 4A$	
Forward Transfer Admittance	Yfs	_	18	_	S	V _{DS} = 5V, I _D = 12A	
Diode Forward Voltage	VsD	_	0.7	1.0	V	$V_{GS} = 0V$, $I_{S} = 5A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}	_	907	_		V 40V V 0V	
Output Capacitance	Coss	_	98	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	38	_		1 - 1.00012	
Gate Resistance	Rg	_	194	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	9.8	_			
Total Gate Charge (V _{GS} = 8V)	Qg	_	18	_	nC	\/ 10\/ I= 6.5A	
Gate-Source Charge	Qgs	_	1.5	_	nc	$V_{DS} = 10V, I_{D} = 6.5A$	
Gate-Drain Charge	Q_{gd}	_	1.8	_			
Turn-On Delay Time	t _{D(ON)}	_	56	_			
Turn-On Rise Time	t _R	_	87	_	20	$V_{DS} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	632	_	ns	$R_G = 6\Omega$, $R_L = 10\Omega$, $I_D = 1A$	
Turn-Off Fall Time	t _F	_	239	_			
Reverse Recovery Time	trr	_	143	_	ns	I _F = 4A, di/dt = 100A/μs	
Reverse Recovery Charge	Qrr		136	_	nC	IF = 4A, di/dt = 100A/µs	

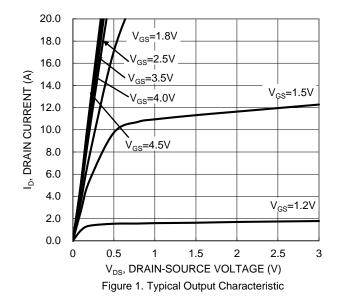
5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

DMN2028UFDF Datasheet number: DS37937 Rev. 3 - 2

Device mounted on FR-4 substrate PC board, 202 copper, with Thirmfull recommended particles.
 Less and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 Short duration pulse test used to minimize self-heating effect.

^{9.} Guaranteed by design. Not subject to product testing.





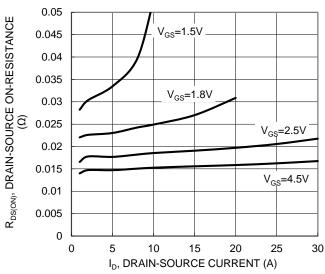


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

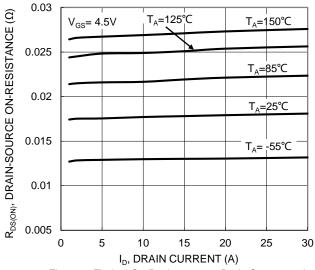


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

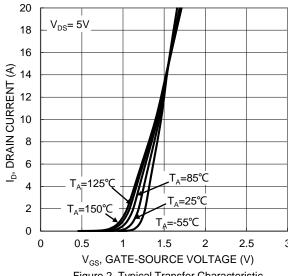
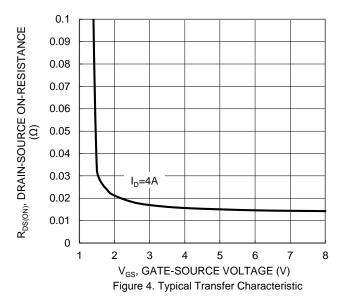


Figure 2. Typical Transfer Characteristic



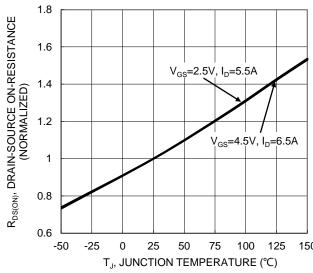


Figure 6. On-Resistance Variation with Temperature



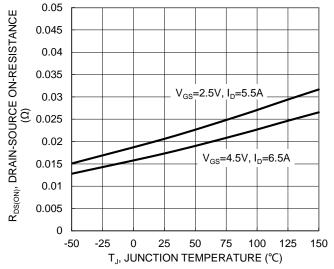
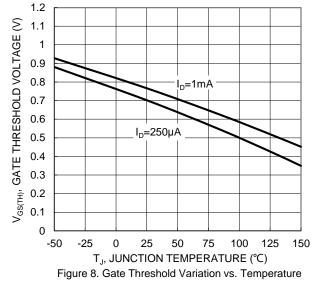
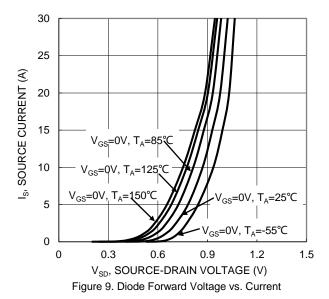
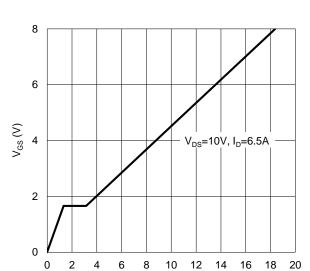


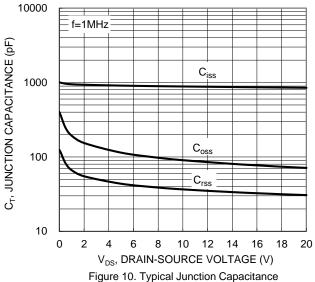
Figure 7. On-Resistance Variation with Temperature

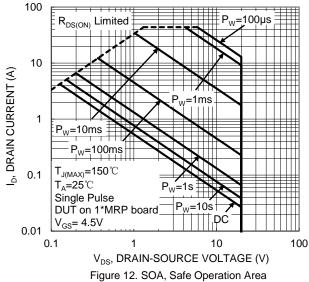






 Q_g (nC) Figure 11. Gate Charge







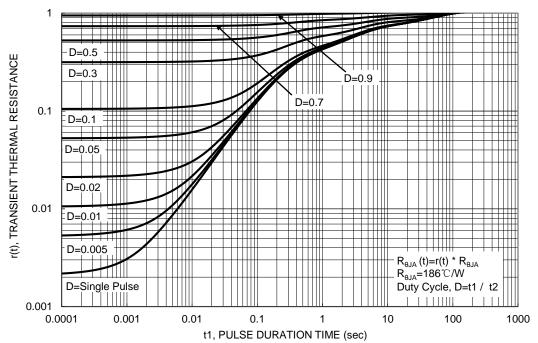


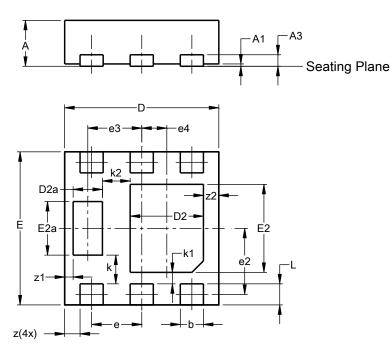
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)

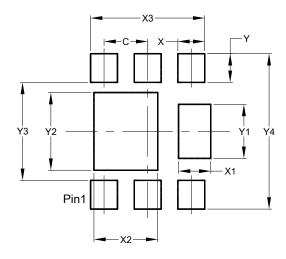


	U-DFN2020-6 (Type F)							
Dim	Min							
Α	0.57	0.63	0.60					
A1	0.00	0.00 0.05 0						
A3	-	-	0.15					
b	0.25	0.35	0.30					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
D2a	0.33	0.43	0.38					
Е	1.95	2.05	2.00					
E2	1.05	1.25	1.15					
E2a	0.65	0.75	0.70					
е		0.65 BS	С					
e2	().863 BS	SC					
е3		0.70 BS	_					
e4	().325 BS	SC					
k		0.37 BS	С					
k1		0.15 BS	С					
k2		0.36 BS	С					
L	0.225	0.325	0.275					
Z	0.20 BSC							
z 1	().110 BS	SC					
z2		0.20 BS	_					
All D	imens	ions in	mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value (in mm)		
С	0.650		
Х	0.400		
X1	0.480		
X2	0.950		
Х3	1.700		
Y	0.425		
Y1	0.800		
Y2	1.150		
Y3	1.450		
Y4	2.300		



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